

SN74AC08-EP 四路双输入正与门

1 特性

- 受控基线
 - 一个组装/测试厂，一个制造厂
- 工作温度范围为 -55°C 至 125°C
- 增强型制造源减少 (DMS) 支持
- 增强型产品变更通知
- 资质谱系†
- 2V 至 6V V_{CC} 运行
- 允许接受输入电压 6V
- 5V 时 t_{pd} 最大值为 7.5ns

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2 说明

SN74AC08 是四路双输入正与门。该器件以正逻辑执行布尔函数 $Y = A \cdot B$ 或 $Y = \overline{A} + \overline{B}$ 。

封装信息

器件型号	封装 ¹	封装尺寸 ²
SN74AC08-EP	D (SOIC , 14)	8.65mm × 3.91mm

- 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
- 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。



图 2-1. 逻辑图，每个逻辑门 (正逻辑)

¹ † 元件资质符合 JEDEC 和行业标准，可在工作温度范围内可靠运行。这包括但不限于高加速应力测试 (HAST) 或偏压 85/85、温度循环、热压器或无偏压 HAST、电迁移、金属间键合寿命和模型化合物寿命。这些资质测试不能作为在超出额定性能和环境限制的条件下使用此组件的依据。



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3 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (September 2003) to Revision A (June 2023)	Page
• 添加了封装信息表、引脚功能表、热信息表、器件功能模式、器件和文档支持部分以及机械、封装和可订购信息部分.....	1

4 Pin Configuration and Functions

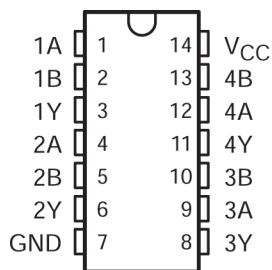


图 4-1. D Package (Top View)

表 4-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
1A	1	Input	Channel 1, Input A
1B	2	Input	Channel 1, Input B
1Y	3	Output	Channel 1, Output Y
2A	4	Input	Channel 2, Input A
2B	5	Input	Channel 2, Input B
2Y	6	Output	Channel 2, Output Y
GND	7	—	Ground
3Y	8	Output	Channel 3, Output Y
3A	9	Input	Channel 3, Input A
3B	10	Input	Channel 3, Input B
4Y	11	Output	Channel 4, Output Y
4A	12	Input	Channel 4, Input A
4B	13	Input	Channel 4, Input B
V _{CC}	14	—	Positive Supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I ¹	Input voltage range	-0.5	$V_{CC} + 0.5$	V
V_O ¹	Output voltage range	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$(V_I < 0 \text{ or } V_I > V_{CC})$		±20 mA
I_{OK}	Output clamp current	$(V_O < 0 \text{ or } V_O > V_{CC})$		±20 mA
I_O	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		±50 mA
	Continuous current through V_{CC} or GND			±200 mA
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)¹

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2	6	V
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V}$	2.1	V
		$V_{CC} = 4.5 \text{ V}$	3.15	
		$V_{CC} = 5.5 \text{ V}$	3.85	
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V}$	0.9	V
		$V_{CC} = 4.5 \text{ V}$	1.35	
		$V_{CC} = 5.5 \text{ V}$	1.65	
V_I	Input voltage	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 3 \text{ V}$	-12	mA
		$V_{CC} = 4.5 \text{ V}$	-24	
		$V_{CC} = 5.5 \text{ V}$	-24	
I_{OL}	Low-level output current	$V_{CC} = 3 \text{ V}$	12	mA
		$V_{CC} = 4.5 \text{ V}$	24	
		$V_{CC} = 5.5 \text{ V}$	24	
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
T_A	Operating free-air temperature	-55	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND for proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

5.3 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74AC08-EP	UNIT
		D (SOIC)	
		14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	86	°C/W

(1) For more information about traditional and new thermal metrics, see the [IC Package Thermal Metrics](#)

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}	$I_{OH} = -50\ \mu\text{A}$		3 V	2.9			2.9		V
			4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
	$I_{OH} = -12\ \text{mA}$		3 V	2.56			2.4		
			4.5 V	3.86			3.7		
			5.5 V	4.86			4.7		
V_{OL}	$I_{OL} = 50\ \mu\text{A}$		3 V	0.002	0.1		0.1		V
			4.5 V	0.001	0.1		0.1		
			5.5 V	0.001	0.1		0.1		
	$I_{OL} = 12\ \text{mA}$		3 V		0.36		0.5		
			4.5 V		0.36		0.5		
			5.5 V		0.36		0.5		
I_I	A or B ports	$V_I = V_{CC}$ or GND	5.5 V		± 0.1		± 1		μA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		2		40		μA
C_i		$V_I = V_{CC}$ or GND	5 V	4.5					pF

5.5 Switching Characteristics, $V_{CC} = 3.3\ \text{V} \pm 0.3\ \text{V}$

over recommended operating free-air temperature range, $V_{CC} = 3.3\ \text{V} \pm 0.3\ \text{V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	7.5	9.5	1	12.5	ns
t_{PHL}			1.5	7	8.5	1	11.5	

5.6 Switching Characteristics, $V_{CC} = 5\ \text{V} \pm 0.5\ \text{V}$

over recommended operating free-air temperature range, $V_{CC} = 5\ \text{V} \pm 0.5\ \text{V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

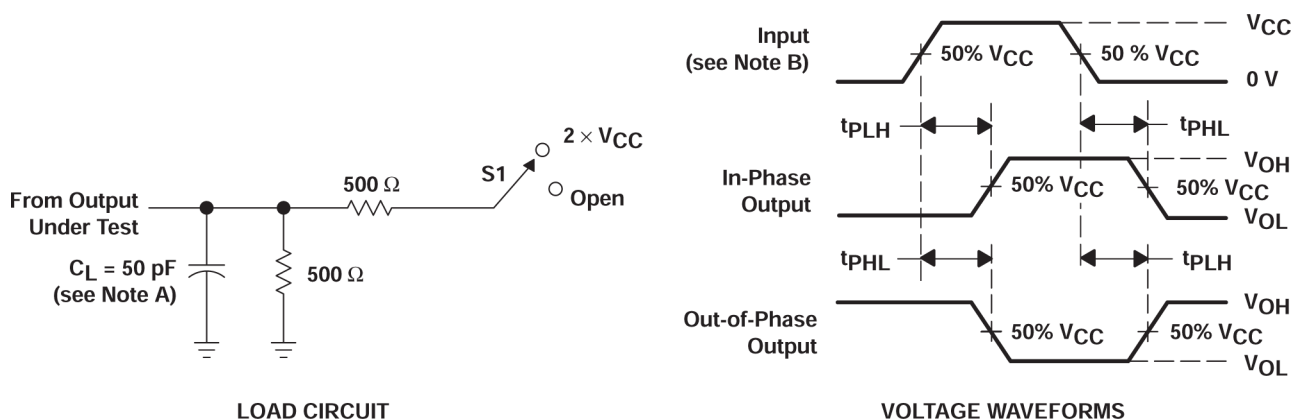
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	5.5	7.5	1	9	ns
t_{PHL}			1.5	5.5	7	1	8.5	

5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	20	pF

6 Parameter Measurement Information



- A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

图 6-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open

7 Detailed Description

7.1 Functional Block Diagram

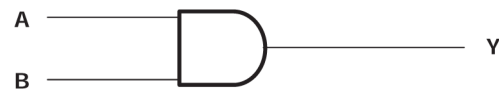


图 7-1. Logic Diagram, Each Gate (Positive Logic)

7.2 Device Functional Modes

表 7-1. Function Table (Each Gate)

INPUTS		OUTPUT Y
A	B	
H	H	H
L	X	L
X	L	L

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

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8.4 静电放电警告



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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AC08MDREP	LIFEBUY	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SAC08MEP	
V62/04615-01XE	LIFEBUY	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SAC08MEP	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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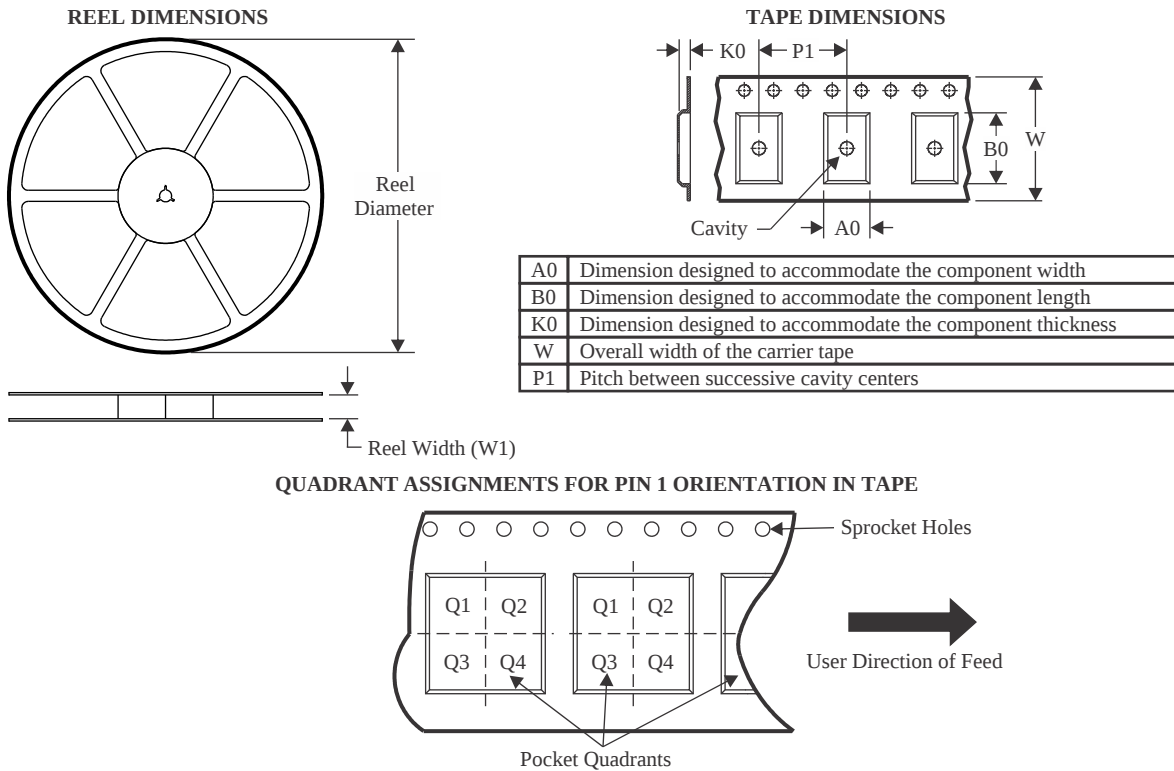
OTHER QUALIFIED VERSIONS OF SN74AC08-EP :

- Catalog : [SN74AC08](#)
- Automotive : [SN74AC08-Q1](#)
- Military : [SN54AC08](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC08MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC08MDREP	SOIC	D	14	2500	333.2	345.9	28.6

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